HI-POWER INFRARED LED SPECIFICATION

HIRPB8-1Gx





Drawn by	Checked by	Approved by



DATE:2009/11/10 REV:A



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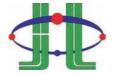
HUEY JANN Infrared High Power LED is made of hi-eff GaAlAs chips with precise package technique which makes excellent heat dissipation to reach the advantages of high radiant output power efficiency, low decay, and long endurance.

FEATERUS

- > Instant light
- Long operating life
- Superior ESD defense
- Low voltage DC operated
- More energy efficient than incandescent and most halogen lamps

TYPICAL APPLICATIONS

- Remote controller
- Monitor illumination
- Security system
- Fire control
- > 3C products
- > Data-transmission
- Special medical



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Explanation of Part Number:

<u>H IR P B 8 - 1 Gx / WPCB</u>

1. H: Huey Jann 2. IR: Infrared LED Type

3. P: High power LED Type 4. Shape distinguish:

B: Lambertian type S: Side emitting type
D: Focusing type E: Focusing type

R: Reflector type

5. Identification no: 6. Appearance:

1:White Diffusion 4:Water Clear

7. Dice kind: 8. Heat conduction type:

G: 850nm For 1000mA Non: emitter type

Gb: 850nm For 500mA /WPCB: with white star type heat sink



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DEVICES

Emitter Type

Item	Lens Color	Dice Source	Color
HIRPB8-1G	Water Clear	GaAlAs/GaAlAs	Infrared
HIRPB8-1Gb	vvater Clear	GaAlAs/GaAlAs	Infrared

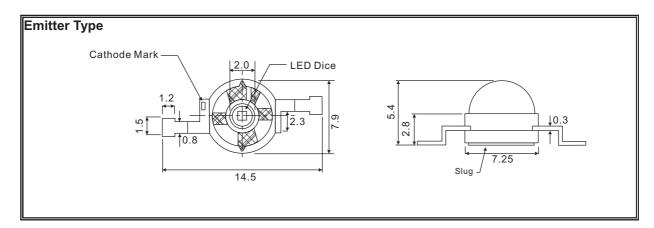
With White Star MCPCB Type

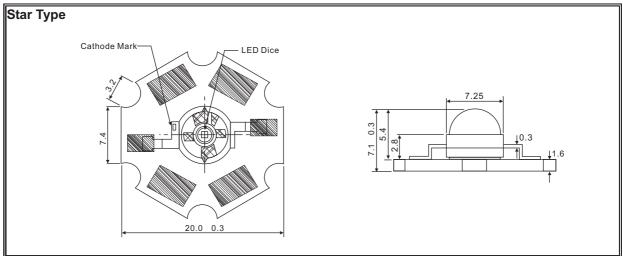
Item	Lens Color	Dice Source	Color
HIRPB8-1G/WPCB	Water Clear	GaAlAs/GaAlAs	Infrared
HIRPB8-1Gb/WPCB	vvater Clear	GaAlAs/GaAlAs	Infrared



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PACKAGE DIMENSIONS:





NOTE:

- 1.All dimensions are in millimeter.
- 2.Lead spacing in measured where the lead emerge from the package.
- 3.prodruded resin under flange is 1.5mm max.
- 4.specifications are subject to change without notice.
- 5. Tolerance is 0.3mm unless otherwise noted.
- 6.Driving LED without heat sinking device is forbidden.
- 7.It is strongly recommended that the temperature of lead be not higher than 55°C.
- 8. Proper current derating must be observed to maintain junction temperature below the maximum.
- 9.LEDs are not designed to be driven in reserve bias.



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BABSOLUTE MAXIMUM RATINGS

TA=25°C

PARAME	TER	SYMBOL	MAX. RATING	UNIT	
Continuous Forward	HIRPB8-1Gx	IF	1000	mΛ	
Current	HIRPB8-1Gbx	115	500	mA	
Peak Forward Current	HIRPB8-1Gx	IFM	1500	mA	
*1	HIRPB8-1Gbx	IFIVI	1000	IIIA	
Reverse Voltage		VR	5	V	
LED Junction Tempera	ture	Tj	120	°C	
Operating Temperature		Topr	-40 ~ +110	°C	
Storage Temperature		Tstg	-40 ~ +120	°C	
Manual Soldering Temperature 260 °C for 5 seconds max. *2 *3					

^{*1.}Duty Ratio=0.1%, Pulse Width=10us.

- *2.Iron soldering high temperature will not cause damage to the dice. But be aware of the high temperature will not only make the epoxy soften but also cause the lead moving and the gold wire broken and even open. So before returning to the normal temperatures PLEASE AVOID any serious pressure on the top of epoxy and lead.
- *3.Measured at leads, lens temperature must not exceed 120°C during lead soldering and slug attach. Soldering by general IR reflow, Vapor phase reflow and wave soldering on this system product is unsuitable. Selective heating of the leads limit lead soldering, such as by hot bar reflow, fiber focussed IR, or hand soldering. The package back plane (slug) may not be attached by soldering, but rather with a thermally conductive adhesive. Electrical insulation between the slug and the board is necessary. Please consult welding matters needing attention.



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ELECTRIC-OPTICAL CHARACTERISTICS FOR HIRPB8-1Gx

TA=25°C

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
View Angle of Half Power	201/2	IF=1000mA		120		deg
Forward Voltage	VF	IF-1000IIIA		1.6	1.9	V
Reverse Current	IR	VR=5V			100	μ A
Radiant Output Power *2	Ро	IF=1000mA	35	70		mw/sr
Peak Emission Wavelength	λр			850		nm
Spectrum Width Of Half Valve	Δλ			40		nm
Rise/Fall Time	Tr/Tf			25/15	35/35	ns
Terminal Capacitance	Ct	V=0V F=1MHz		40		pF

^{*2.}Tolerance: 15% HUEY-JANN measuring equipment: EXELTRON 2001. 2.S370 made by U.D.T.



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ELECTRIC-OPTICAL CHARACTERISTICS FOR HIRPB8-1Gbx

TA=25°C

PARAMETER	SYMBOL	TEST CONDITION	MIN	ТҮР	MAX	UNIT
View Angle of Half Power	201/2	IE-500m A		120		deg
Forward Voltage	VF	IF=500mA		1.7	2.0	V
Reverse Current	IR	VR=5V			100	μ Α
Radiant Output Power *2	Ро	IF=500mA	25	50		mw/sr
Peak Emission Wavelength	λр			850		nm
Spectrum Width Of Half Valve	Δλ			40		nm
Rise/Fall Time	Tr/Tf			25/15	35/35	ns
Terminal Capacitance	Ct	V=0V F=1MHz		40		pF

^{*2.}Tolerance: 15% HUEY-JANN measuring equipment: EXELTRON 2001. 2.S370 made by U.D.T.



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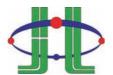
PRELIABILITY TEST

Endurance Test

Test Item	Reference Standard	Test Conditions	Result
Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	Connect with a power if=500~1000mA Ta=Under room temperature Test Time=1,000hrs	0/22
High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+85°C 5°C RH=80% ~ 85% Test Time=1,000hrs	0/22
High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+120°C 5°C Test Time=1,000hrs	0/22
Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-40°C 5°C Test Time=1,000hrs	0/22

*Failure Criteria:

- 1. VF arise ≥10%
- 2. IV decline ≥30%
- 3. A failure is an LED that is open or shorted



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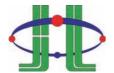
PRELIABILITY TEST

> Environmental Test

Test Item	Reference Standard	Test Conditions	Result
Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-40°C ~ +25°C ~ +85°C ~ +25°C 60min 20min 60min 20min Test Time=200cycle	0/22
Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010	-40°C 5°C ~ +110°C 5°C 20min 20min Test Time=200cycle	0/22

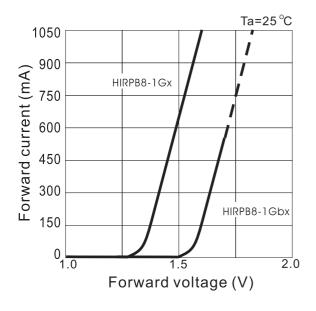
^{*}Failure Criteria:

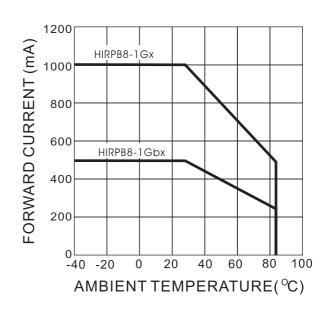
- 1. VF arise ≥ 10%
- 2. IV decline $\geq 30\%$
- 3. A failure is an LED that is open or shorted

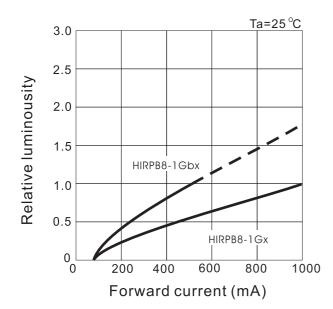


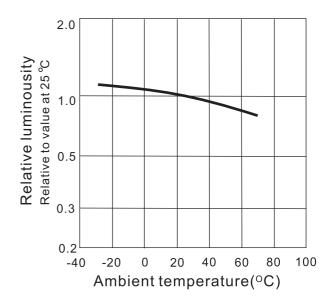
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TYPICAL ELECTRICAL OPTICAL CHARACTERISTICS CURVES





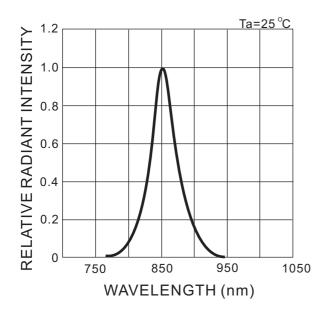


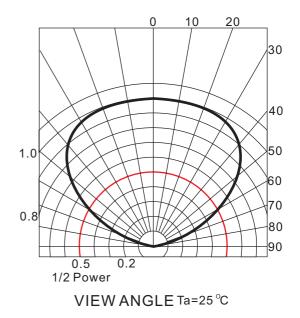




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TYPICAL ELECTRICAL OPTICAL CHARACTERISTICS CURVES







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LED VF Bin Selection

HIRPB8-1Gx

Brightness Code				
BIN CODE	Brightne	ess in Im		
DIN CODE	Minimum	Maximum		
b	1.4	1.6		
С	1.6	1.8		
d	1.8	2.0		

NOTE:

- 1.Test Condition at IF=500~1000mA.
- 2. Voltage tolerance for each bin limit is $\pm 0.03 \text{V}$

HIRPB8-1Gbx

Brightness Code				
BIN CODE	Brightness in Im			
BIN CODE	Minimum	Maximum		
b	1.4	1.6		
С	1.6	1.8		
d	1.8	2.0		

Brightness Bin Selection

HIRPB8-1Gx

Brightness Code				
BIN CODE	Brightne	ess in Im		
DIN CODE	Minimum	Maximum		
4	50	60		
5	60	70		
6	70	80		
7	80	100		

NOTE:

- 1. Test Condition at IF=500~1000mA.
- 2. Brightness tolerance for each bin limit is $\pm 15\%$

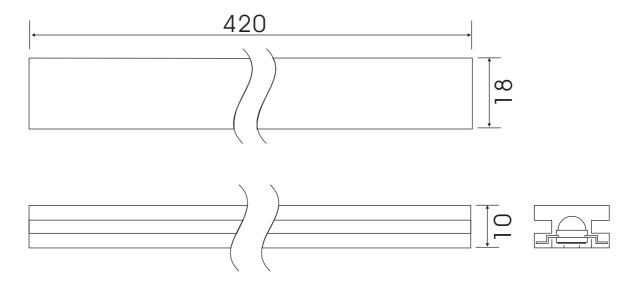
HIRPB8-1Gbx

Brightness Code				
BIN CODE	Brightness in Im			
DIN CODE	Minimum	Maximum		
2	30	40		
3	40	50		
4	50	60		



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Package Dimension For Emitter Type



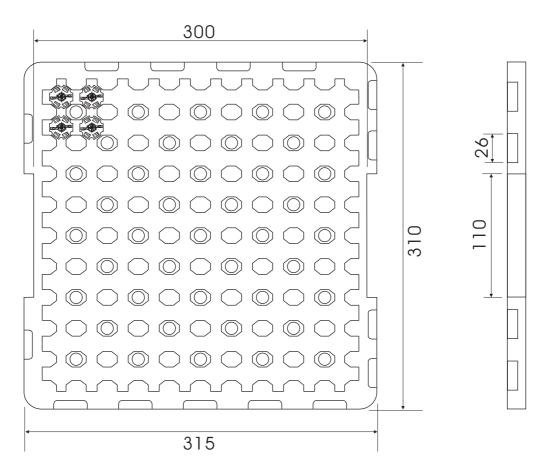
NOTE:

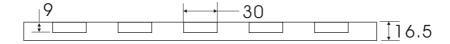
- 1. Dimensions are specified as follows: mm.
- 2. Tolerance is 0.3mm unless otherwise noted.
- 3. 50 pcs emitters per tube.
- 4. 80 tubes per inside box.
- 5. 4 inside box per outside box.



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Package Dimension For Star Type





NOTE:

- 1. Dimensions are specified as follows: mm.
- 2. Tolerance is 0.3mm unless otherwise noted.
- 3. 100pcs star per tray.
- 4. 10 trays per box.

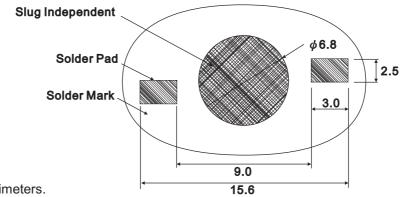


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Requirements to user For Emitter Type

The LED products by HUEY-JANN is designed, manufactured, and sold aiming at high standard quality and reliability, however, reliability of electronic apparatus is seen as a product of reliability superior to HUEY-JANN and using status at users. From this point, HUEY-JANN requests user's for following things.

Recommended Solder Pad Design For Emitter Type



Note:

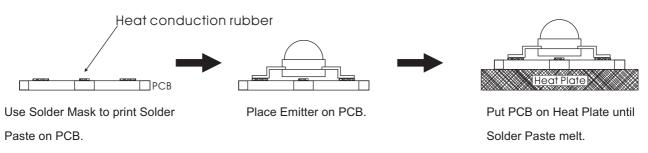
- 1.All dimensions are in millimeters.
- 2. Electrical isolation is required between Slug and Solder Pad.



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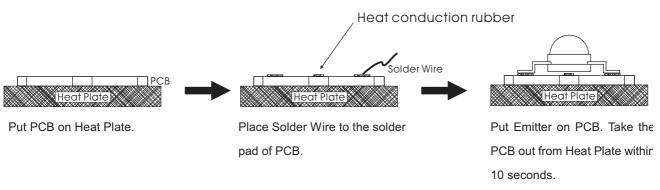
Heat Plate Soldering Condition For Emitter Type

a. Soldering Process for Solder Paste



- 1. The Solder Paste sould be melted within 10 seconds.
- 2. Take out PCB out from Heat Plate within 15 seconds.

b. Soldering Process for Solder Wire



NOTE:

- 1.Heat plate temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.

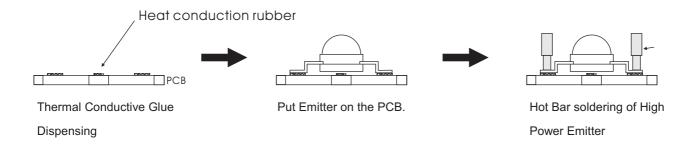


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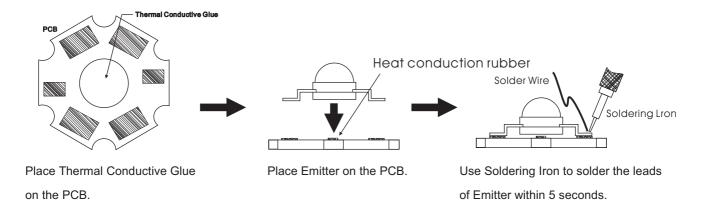
Soldering Process For Hot Bar For Emitter Type



NOTE:

- 1.Hot Bar temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.

Manual Hand Soldering For Emitter Type

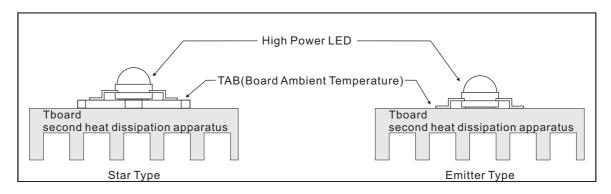


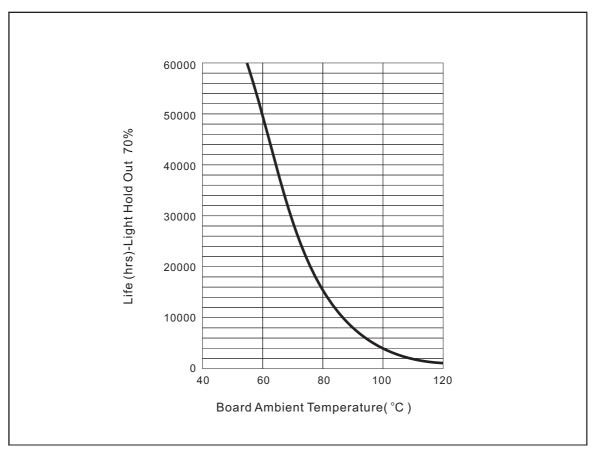
- 1.Solder tip temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- 2. Avoiding damage to the emitter or to the PCB dielectric layer. Damage to the epoxy layer can cause
- 3.Do not let the solder contact from solder pad to back-side of PCB. This one will cause a short circuit and damage emitter.



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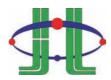
TAB Temperature - Life Characteristics Curves





^{*}Board Ambient Temperature Tolerance 5°C.

^{*}This document is for reference only.



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^{*}The TAB is the stable testing value for the product lighted 100% after one hour.